



HJ127

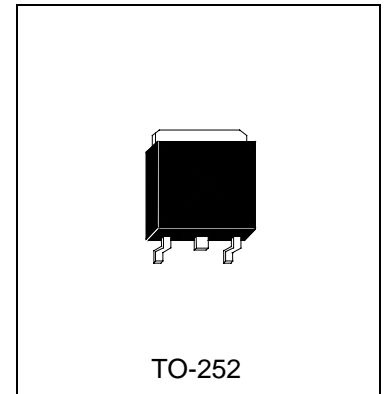
PNP EPITAXIAL PLANAR TRANSISTOR

Description

- High DC current gain
- Built-in a damper diode at E-C

Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
 - Storage Temperature -55 ~ +150 °C
 - Junction Temperature +150 °C
- Maximum Power Dissipation
 - Total Power Dissipation (Tc=25°C) 20 W
- Maximum Voltages and Currents
 - BVCBO Collector to Base Voltage -100 V
 - BVCEO Collector to Emitter Voltage -100 V
 - BVEBO Emitter to Base Voltage -5 V
 - IC Collector Current -5 A

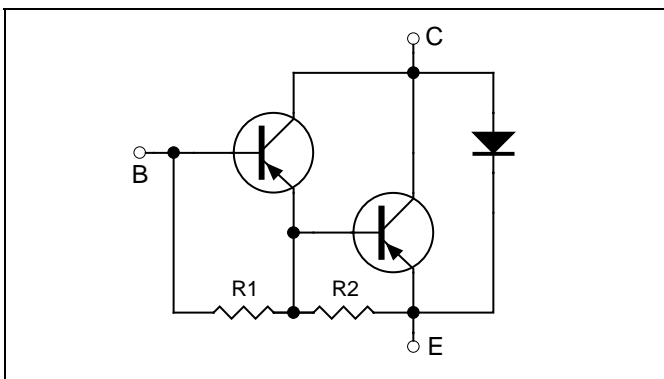


Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-100	-	-	V	IC=-1mA, IE=0
BVCEO	-100	-	-	V	IC=-30mA, IB=0
BVEBO	-5	-	-	V	IE=-1mA, IC=0
ICBO	-	-	-10	uA	VCB=-100V, IE=0
IEBO	-	-	-2	mA	VEB=-5V, IC=0
ICEX	-	-	-10	uA	VCE=-100V, VBE(off)=-1.5V
*VCE(sat)1	-	-	-2	V	IC=-4A, IB=-16mA
*VCE(sat)2	-	-	-4	V	IC=-8A, IB=-80mA
*VBE(sat)	-	-	-4.5	V	IC=-8A, IB=-80mA
*VBE(on)	-	-	-2.8	V	VCE=-4V, IC=-4A
*hFE1	1	-	12	K	VCE=-4V, IC=-4A
*hFE2	100	-	-	-	VCE=-4V, IC=-8A
Cob	-	-	300	pF	VCB=-10V, f=0.1MHz

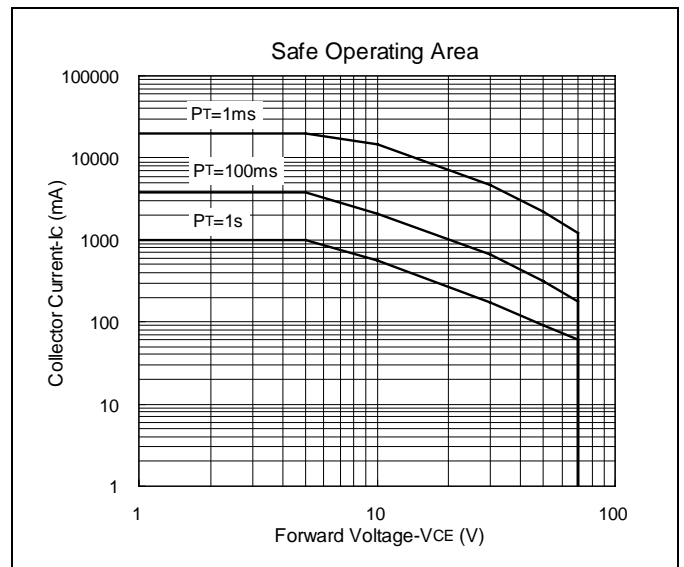
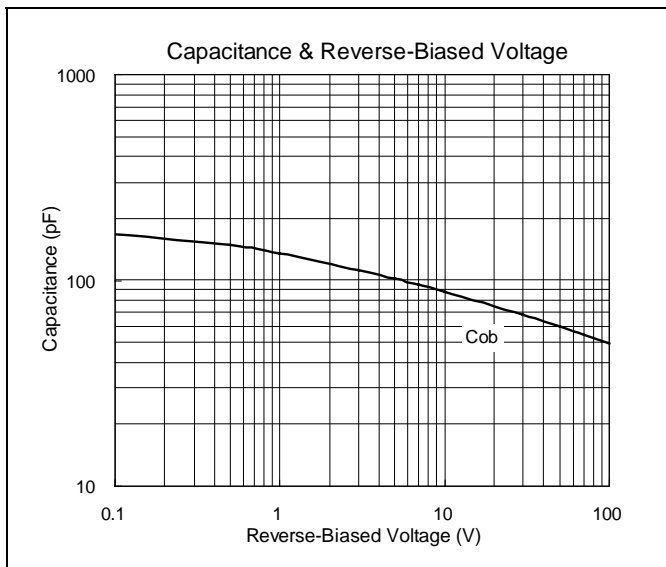
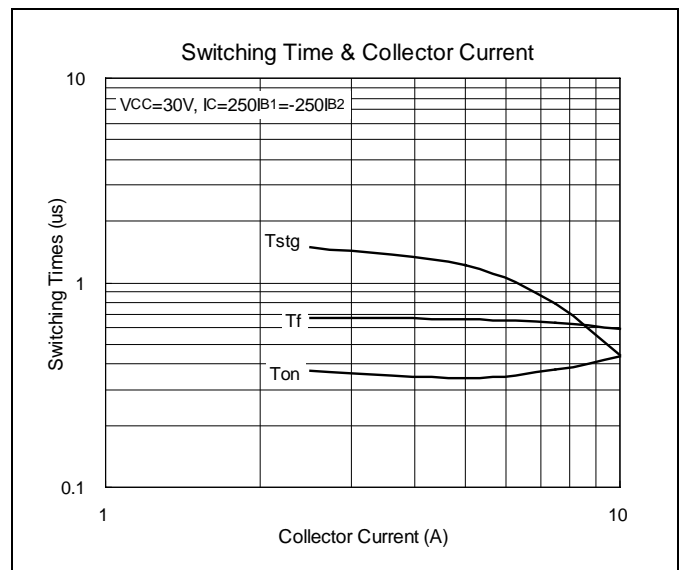
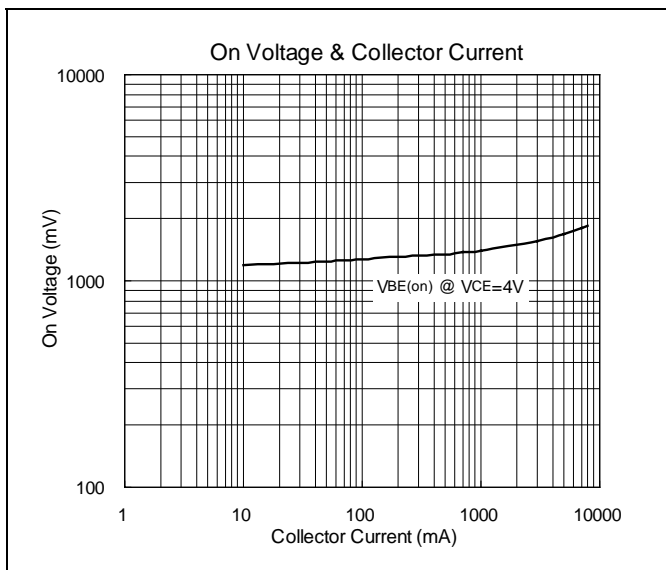
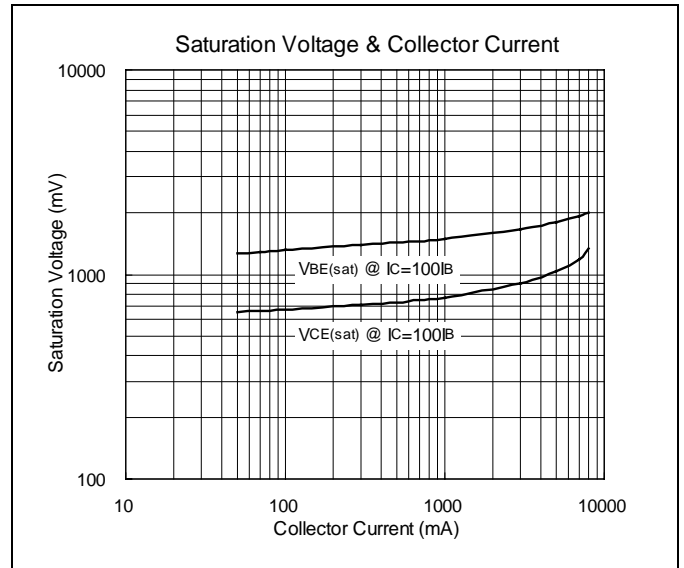
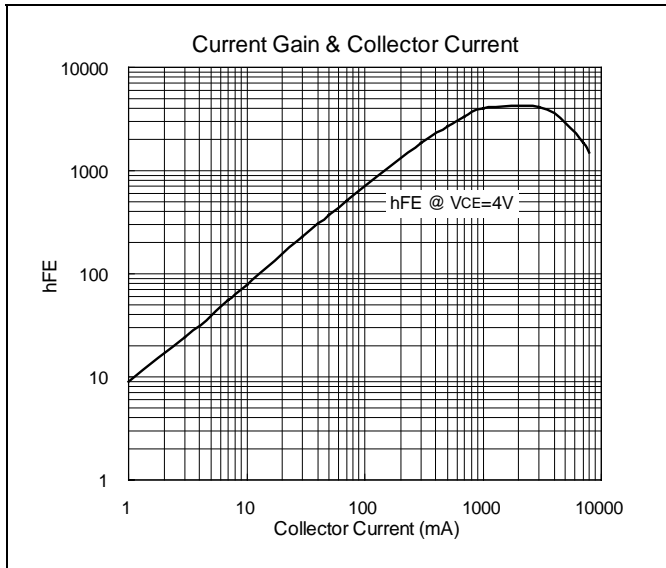
*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

Darlington Schematic



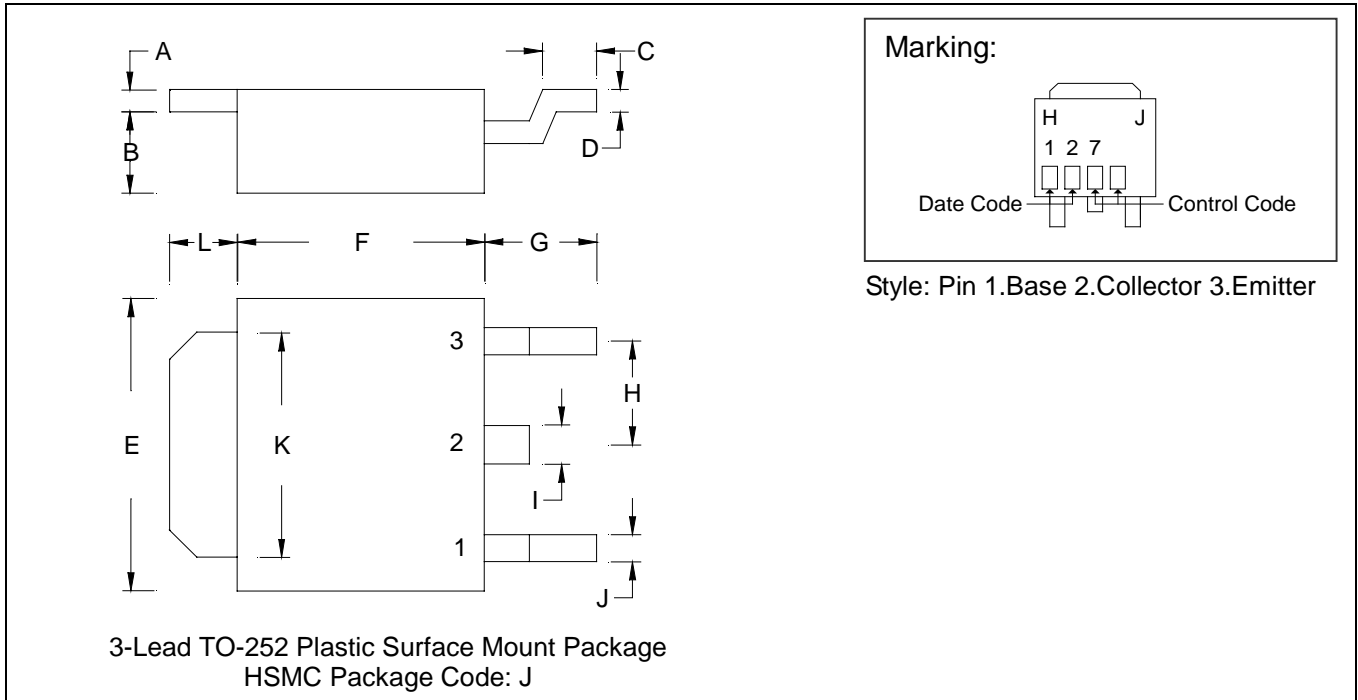


Characteristics Curve





TO-252 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0177	0.0217	0.45	0.55	G	0.0866	0.1102	2.20	2.80
B	0.0650	0.0768	1.65	1.95	H	-	*0.0906	-	*2.30
C	0.0354	0.0591	0.90	1.50	I	-	0.0354	-	0.90
D	0.0177	0.0236	0.45	0.60	J	-	0.0315	-	0.80
E	0.2520	0.2677	6.40	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2125	0.2283	5.40	5.80	L	0.0551	0.0630	1.40	1.60

- Notes:**
- 1.Dimension and tolerance based on our Spec. dated May. 05,1996.
 - 2.Controlling dimension: millimeters.
 - 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 - 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy ; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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